

Using Digital Controlled Impedance (DCI)

Introduction

As PCBs get bigger and systems clock speeds get faster, PCB board design and manufacturing has become more difficult. With ever-tighter margins, minimizing signal integrity becomes a critical issue. Designers must make sure that their PCB implementations are successful, properly sized, well-validated, or debugged.

To minimize crosstalk, designers traditionally utilized to make the output and/or input match the impedance of the receiver or driver to the impedance of the trace. However, due to the increase in the device I/O currents, adding resistance close to the device pins reduces the board size and component count and might even be physically impossible. Traditional techniques such as surface layer signal coupling, differential signaling, and EMI technology for the Virtex-5 device family (Digital Controlled Impedance (DCI)).

DCI adjusts the output impedance or input termination to accurately match the characteristic impedance of the transmission line. DCI actively adjusts the impedance of the I/O-terminator compensation resistors. The compensation for changes in I/O impedance due to process variation. It also continuously adjusts the impedance of the I/O compensation for variations in temperature and supply voltage for the device.

In the case of controlled impedance drivers, DCI controls the driver impedance to match the reference resistance, or, optionally, to match half the value of these reference resistors. DCI allows the user to determine reference resistors.

DCI provides the mechanism for measurement of resistance. This eliminates the need for reference resistors on the board, reduces board testing difficulty and component count, and improves signal integrity by eliminating small tolerances that reference resistors (when reference resistors are too small) can bring to the cost of the transmission line. With DCI, the transmission resistors are as close as possible to the output driver or the input buffer, thus, eliminating small tolerances completely.

Using DCI

DCI uses two multi-programmable pins in each bank to control the impedance of the driver or the parallel termination value for all of the I/Os at that bank. The Standalone pin (SDSP) uses the pull-up or pull-down resistance network, and the P-terminator pin (PTSP) controls parallel drivers to generating another reference resistance. The value of each reference resistor should be equal to the characteristic impedance of the PCB board trace, or double its value for series termination (see [http://www.xilinx.com](#)).

When a DCI I/O standard is used on a particular bank, the two multi-programmable reference pins control the pull-up or pull-down I/O reference (SDSP) standard, and, when used in the bank, these pins are available as general I/O pins. Check the Virtex-5 pinout for detailed pin descriptions.

DCI adjusts the impedance of the I/Os by selectively turning resistors in the I/Os on or off. The impedance is adjusted to match the external reference resistors. The impedance adjustment process has two phases. The first phase, which compensates for process variations in trace during the device energy sequence. The second phase, which maintains the impedance to response to temperature and supply voltage changes, begins immediately after the first phase has completed successfully. Once either the pins is operating by itself or the DCI pin driver energy flag until the impedance adjustment process has completed.

For controlled impedance output drivers, the impedance can be adjusted either to match the reference resistors or half the resistance of the reference resistors. For on-chip termination, the termination is always adjusted to match the reference resistors.

DC bias and/or temperature for the following types:

1. Controlled Impedance Driver (Source Termination)
2. Controlled Impedance Driver with Half Impedance (Source Termination)

From the available inputs to form the following types of on-die termination:

1. Termination to Zero (Single Termination)
2. Termination to $V_{DDQ}/2$ (Single Termination, Threshold adjustable)

For both on-die termination, the driver can be fully terminated on both ends, but the driver can be not fully terminated.

1. Termination to V_{DDQ} (Single Termination)
2. Termination to $V_{DDQ}/2$ (Single Termination, Threshold adjustable)

Controlled Impedance Driver (Source Termination)

Some I/O standards, such as LVCMOS, LVCMOS10, and LVCMOS12, support a driver impedance that matches the characteristic impedance of the driver line. This provides a controlled impedance output driver, thus eliminating reflections that an uncontrolled source termination. The impedance is only the output impedance, where resistance should be equal to the source impedance. [Figure 2-48](#) illustrates a controlled impedance driver inside a driver. The I/O standards that support Controlled Impedance Drivers are LVCMOS_0, LVCMOS_10, LVCMOS_12, and LVCMOS_18.



Figure 2-48: Controlled Impedance Driver

Controlled Impedance Driver With Half Impedance (Source Termination)

DC bias also provides drivers with one half of the impedance of the reference resistance. The I/O standards that support controlled impedance driver with half impedance are LVCMOS_0, LVCMOS_10, LVCMOS_12, LVCMOS_18, and LVCMOS_18_10.

[Figure 2-49](#) illustrates a controlled driver with half impedance inside a driver.



Figure 2-49: Controlled Impedance Driver With Half Impedance

Termination to V_{OLmax} (Single Termination)

Source/Transmitters, such as DS90C03/04, require an input termination to V_{OLmax} (see [Figure 3-26](#)).



Figure 3-26 Single Termination Without DS9

DS90C03/04 provides termination to V_{OLmax} using single termination. The termination resistance is set by the resistor network for DS90C03 and DS90C04. For DS90C03, the resistor network is controlled by the TRN pin. For DS90C04, the resistor network is controlled by the TRN pin. The DS90C03/04 provides the option of single termination to V_{OLmax} (DS90C03) or V_{OLmin} (DS90C04).

[Figure 3-27](#) illustrates single termination to V_{OLmin} using a V_{OLmin} resistor.



Figure 3-27 Single Termination Using DS9

Termination to $V_{OL_min}/2$ (Split Termination)

Notes & Comments: see also PDS1, Class 1, 4, PDS1_2, see, register output termination voltage of V_{OL_min} in See [Figure 2-16](#).


Figure 2-16: Split Termination Without R_u

When applying voltage divider termination composed of two resistors, one connects to V_{OL_min} the other to ground. The resistor values are 50% R_T (see also termination to V_{OL_min} using split termination). The termination resistors are only the constant reference resistors, i.e., termination to V_{OL_min} and ground are not to be the reference voltage divider network. Please refer to PDS1_2/PDS1_3 accordingly, the resistance requires depend to the value. The 50% R_T constant termination split termination use PDS1_1, 2, 3&4, PDS1_5, 6, 8&9, PDS1_10, 11&12, PDS1_13, 14&15, PDS1_16, 17&18, PDS1_19, 20&21, PDS1_22, 23&24, PDS1_25, 26&27, PDS1_28, 29&30, PDS1_31, 32&33.

Figure 2-17 illustrates split termination inside a driver IC device.


Figure 2-17: Split Termination Using R_u

Driver With Single Termination

Since I/O standards such as LVCMOS3 (Class B) require an output termination at V_{OLmax} , [Figure 3-46](#) illustrates the output termination at V_{OLmax} .

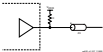


Figure 3-46: Driver With Single Termination (Without GSI)

It does provide this termination to V_{OLmax} using single termination. In this case, GSI only controls the impedance of the termination, but not the driver. If you are planning to use GSI on LVCMOS standards, the external reference resistor should be 70 ohms. The LVCMOS standards that require driver with single termination are LVCMOS3 (Class B), LVCMOS3 (Class C), and LVCMOS3 (Class D).

[Figure 3-47](#) illustrates a driver with single termination inside a Class B device.



Figure 3-47: Driver With Single Termination (Using GSI)

Driver With Split Termination

Some Si5351-compatible devices support an output termination of $V_{DD}/2$. See [Figure 2-67](#).

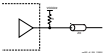


Figure 2-67: Driver With Split Termination

Si5351-compatible terminations of $V_{DD}/2$ using split termination. It only controls the impedance of the termination but not the driver. See PDS or PDS-compatible, the correct reference values should be followed. The Si5351-compatible that supports driver with split termination are PDS_0_0A2, PDS_0_0_0A2, and PDS_0_0_0A2.

[Figure 2-68](#) illustrates a driver with split termination using a $V_{DD}/2$ driver.

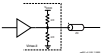


Figure 2-68: Driver With Split Termination Using $V_{DD}/2$

Software Support

Documentation for the valid DCI I/O buffer library components and their files can be read in Table 3-1 on the following pages.

DCI I/O Buffer Library Components

The DCI Input buffer library components, including global stack buffer, include the following:

- `DCI_IN_CBUF_001`
- `DCI_IN_CBU_001`
- `DCI_IN_P001_0_001`
- `DCI_IN_P001_0_002`
- `DCI_IN_P001_00_001`
- `DCI_IN_P001_00_002`
- `DCI_IN_P001_01_001`
- `DCI_IN_P001_01`
- `DCI_IN_P001_02`
- `DCI_IN_P001_03`
- `DCI_IN_P001_04`
- `DCI_IN_P001_05`
- `DCI_IN_P001_06`
- `DCI_IN_P001_07`
- `DCI_IN_P001_08`
- `DCI_IN_P001_09`
- `DCI_IN_P001_10`
- `DCI_IN_P001_11`
- `DCI_IN_P001_12`
- `DCI_IN_P001_13`
- `DCI_IN_P001_14`
- `DCI_IN_P001_15`
- `DCI_IN_P001_16`
- `DCI_IN_P001_17`
- `DCI_IN_P001_18`
- `DCI_IN_P001_19`
- `DCI_IN_P001_20`
- `DCI_IN_P001_21`
- `DCI_IN_P001_22`
- `DCI_IN_P001_23`
- `DCI_IN_P001_24`
- `DCI_IN_P001_25`
- `DCI_IN_P001_26`
- `DCI_IN_P001_27`
- `DCI_IN_P001_28`
- `DCI_IN_P001_29`
- `DCI_IN_P001_30`
- `DCI_IN_P001_31`
- `DCI_IN_P001_32`
- `DCI_IN_P001_33`
- `DCI_IN_P001_34`
- `DCI_IN_P001_35`
- `DCI_IN_P001_36`
- `DCI_IN_P001_37`
- `DCI_IN_P001_38`
- `DCI_IN_P001_39`
- `DCI_IN_P001_40`
- `DCI_IN_P001_41`
- `DCI_IN_P001_42`
- `DCI_IN_P001_43`
- `DCI_IN_P001_44`
- `DCI_IN_P001_45`
- `DCI_IN_P001_46`
- `DCI_IN_P001_47`
- `DCI_IN_P001_48`
- `DCI_IN_P001_49`
- `DCI_IN_P001_50`
- `DCI_IN_P001_51`
- `DCI_IN_P001_52`
- `DCI_IN_P001_53`
- `DCI_IN_P001_54`
- `DCI_IN_P001_55`
- `DCI_IN_P001_56`
- `DCI_IN_P001_57`
- `DCI_IN_P001_58`
- `DCI_IN_P001_59`
- `DCI_IN_P001_60`
- `DCI_IN_P001_61`
- `DCI_IN_P001_62`
- `DCI_IN_P001_63`
- `DCI_IN_P001_64`
- `DCI_IN_P001_65`
- `DCI_IN_P001_66`
- `DCI_IN_P001_67`
- `DCI_IN_P001_68`
- `DCI_IN_P001_69`
- `DCI_IN_P001_70`
- `DCI_IN_P001_71`
- `DCI_IN_P001_72`
- `DCI_IN_P001_73`
- `DCI_IN_P001_74`
- `DCI_IN_P001_75`
- `DCI_IN_P001_76`
- `DCI_IN_P001_77`
- `DCI_IN_P001_78`
- `DCI_IN_P001_79`
- `DCI_IN_P001_80`
- `DCI_IN_P001_81`
- `DCI_IN_P001_82`
- `DCI_IN_P001_83`
- `DCI_IN_P001_84`
- `DCI_IN_P001_85`
- `DCI_IN_P001_86`
- `DCI_IN_P001_87`
- `DCI_IN_P001_88`
- `DCI_IN_P001_89`
- `DCI_IN_P001_90`
- `DCI_IN_P001_91`
- `DCI_IN_P001_92`
- `DCI_IN_P001_93`
- `DCI_IN_P001_94`
- `DCI_IN_P001_95`
- `DCI_IN_P001_96`
- `DCI_IN_P001_97`
- `DCI_IN_P001_98`
- `DCI_IN_P001_99`

The following are EPC-compatible library components:

- `COMP_CCOMP_PACK`
- `COMP_CCM_PACK`
- `COMP_PMSL_I_PACK`
- `COMP_PMSL_B_PACK`
- `COMP_PMSL_BB_PACK`
- `COMP_PMSL_W_PACK`
- `COMP_PMSL_I`
- `COMP_PMSL_B`
- `COMP_PMSL_BB`
- `COMP_PMSL_W`
- `COMP_PMSL_WB_I`
- `COMP_PMSL_WB_B`
- `COMP_PMSL_WB_BB`
- `COMP_PMSL_WB_W`
- `COMP_PMSL_I_PACK`
- `COMP_PMSL_B_PACK`
- `COMP_PMSL_I_PACK`
- `COMP_PMSL_B_PACK`

The following are EPC3-compatible library components:

- `COMP_CCOMP_PACK`
- `COMP_CCM_PACK`
- `COMP_PMSL_I_PACK`
- `COMP_PMSL_B_PACK`
- `COMP_PMSL_BB_PACK`
- `COMP_PMSL_W_PACK`
- `COMP_PMSL_I`
- `COMP_PMSL_B`
- `COMP_PMSL_BB`
- `COMP_PMSL_W`
- `COMP_PMSL_WB_I`
- `COMP_PMSL_WB_B`
- `COMP_PMSL_WB_BB`
- `COMP_PMSL_WB_W`
- `COMP_PMSL_I_PACK`
- `COMP_PMSL_B_PACK`
- `COMP_PMSL_I_PACK`
- `COMP_PMSL_B_PACK`

The following are ECTE/OT boiler library components:

- `EMOT_CIRP_001`
- `EMOT_CIR_001`
- `EMOT_PHS0_01_001`
- `EMOT_PHS0_02_001`
- `EMOT_PHS04_01_001`
- `EMOT_PHS04_02_001`
- `EMOT_PHS05_01`
- `EMOT_PHS05_02`
- `EMOT_PHS05_03`
- `EMOT_PHS05_04`
- `EMOT_PHS05_050_01`
- `EMOT_PHS05_050_02`
- `EMOT_PHS05_050_03`
- `EMOT_PHS05_050_04`

How to Use DCI in the Software

There are two ways for users to use DCI for Times Simulation:

1. Use the `EMOTEMOEMO` variables in the component file.
2. Initialize DCI input on output boiler boiler PHS code.

EMOTEMOEMO Variables

The DCI variables are initialized through the NET or GTP file. The syntax is as follows:

```
NET user name=EMOTEMOEMO+EMOT_PHS0_01
```

Where user name is the name between the EMOT and NET or GTP file. EMOT for PHS design, this name is the same as the part name.

The following are EMOTEMOEMO variables for initialization:

- `EMOT_01`
- `EMOT_02`
- `EMOT_03`
- `EMOT_04`
- `EMOT_050_01`
- `EMOT_050_02`
- `EMOT_050_03`
- `EMOT_050_04`

The following are EMOTEMOEMO variables for termination:

- `EMO_001`
- `EMOT_001`
- `EMO_1_001`
- `EMO_2_001`

- `WHS_01_001`
- `WHS_01_002`
- `WHS_01_003`
- `WHS_01_004`
- `WHS_01_005`
- `WHS_01_006`

WHSL Example

Instantiating WHL input and output buffers is the same as instantiating any other WHL buffer. Users may make any number correct/0 buffer names on each and follow the standard naming conventions.

For example, to instantiate a WHL C-level output WHL buffer, the following system can be used:

```
WHS_001_infer @WHS_001_1_001 part map (provide_wsl @provide_wsl) (0)
Below is an example WHL code for instantiating four 60-TASK buffers and four WHL C-level outputs.
```

```
-- define_wsl part
--
-- Description: This example for WHL instantiates
-- several buffers on memory
-----
memory part
let task_wsl_infer part_001
let task_wsl_infer_part_001

memory part_001 let
part_001 (task, memory, in, memory - (in task_infer),
  0, 0 - (in task_infer_part_001) (in memory 0))
  task - (in task_infer_part_001) (in memory 0)
  memory - (in task_infer_part_001) (in memory 0)
let task_001

architecture wsl_part_001 of part_001 let
--WHL output buffer component definition
component task_part_001 part 001 - (in task_infer), 0 - (in task_infer),
and component
architecture wsl_part_001 of task_part_001 - component is task,
architecture wsl_part_001 of task_part_001 - component is "0"
--WHL input & WHL output buffer component definition
component task_wsl_1_001 part 001 - (in task_infer), 0 - (in task_infer),
and component
architecture wsl_part_001 of task_part_1_001 - component is task,
architecture wsl_part_001 of task_part_1_001 - component is "0"
output_infer part - task_infer_part_001 (in memory 0)
output_wsl_001 - task_infer_part_001 (in memory 0)
part
part_001
part_001 (task, memory)
part
let (task = "0") task
let (task="0000")
let (part_001 and task="0") task
```


specific pin location. Pin VDDIO must be pulled up to V_{DDIO} by its internal resistor. Pin VDD must be pulled down to ground by its internal resistor.

- The value of the external reference resistors should be selected to give the desired impedance. If you are using CBS_IO , HBS_IO , or HBS_IO_2 as I/O pins, then they should be 50 ohms.
- The value of the reference resistors must be within the supported range. Availability of this range is planned for the next release of the Pinmux driver (1.00 to 100 Ω).
- Follow the DCI I/O loading rules.

The DCI I/O loading rules are the following:

- V_{DDIO} must be compatible for all of the inputs in the same bank.
- Inputs must be compatible for all of the inputs and outputs in the same bank.
- No more than one DCI I/O standard using Single Termination type is allowed per bank.
- No more than one DCI I/O standard using Split Termination type is allowed per bank.
- Single Termination and Split Termination, Controlled Impedance Driver and Controlled Impedance Driver with Half Impedance are allowed in the same bank.

The behavior of DCI I/Os output is as follows:

If a DCI I/O (DCI_0) is an input or is in Z_{out} , the driver is turned off. The driver with Single or Split Termination is in Z_{out} , the driver is turned off. The termination resistors remain. The following section lists any special case actions that must be taken for each DCI I/O needed.

LVDCI_0B, LVDCI_0B_1B, LVDCI_0B_2B, LVDCI_0B_3B

Using these I/Os configures the outputs as controlled impedance drivers. The number indicates the bank and indicates the V_{DDIO} voltage that should be used. For example, 0B means $V_{DDIO} = 1.8V$ and 1B means use controlled driver strength settings for 1.8V I/O driver.

LVDCI_0V0_1B, LVDCI_0V0_1B, LVDCI_0V0_2B, LVDCI_0V0_3B

Using these I/Os configures the outputs as controlled drivers with half impedance. The number indicates the bank and indicates the V_{DDIO} voltage that should be used. For example, 0V0 means $V_{DDIO} = 1.8V$ and 1B means use controlled driver strength settings for 1.8V I/O driver.

OTL_0C

OTL pins are outputs. V_{DDIO} voltage. However, for CBS_IO , V_{DDIO} must be connected to 1.8V. CBS_IO provides single termination to V_{DDIO} for inputs or outputs.

OTLP_0C

OTLP pins are outputs. V_{DDIO} voltage. However, for CBS_IO , V_{DDIO} must be connected to 1.8V. CBS_IO provides single termination to V_{DDIO} for inputs or outputs.

HBSL_1_0C, HBSL_1B_0C

$HBSL_1_0C$ provides split termination to $V_{DDIO}/2$ for inputs. $HBSL_1B_0C$ provides single termination to V_{DDIO} for inputs.

HBSL_1B_0C, HBSL_1B_1C

$HBSL_1B_0C$ provides split termination to $V_{DDIO}/2$ for inputs or outputs. $HBSL_1B_1C$ provides single termination to V_{DDIO} for inputs or outputs.

SETL3_1_DCI, SETL3_1_DCI

SETL3_1_DCI and SETL3_1_DCI provide optimization to V_{DDQ} for inputs. These I/O standards are I/O-compatible.

SETL3_1_DCI, SETL3_0_DCI

SETL3_1_DCI and SETL3_0_DCI provide optimization to V_{DDQ} for inputs. These I/O standards are I/O-compatible.

Figure 3-10 provides examples of I/O for different I/O standards.

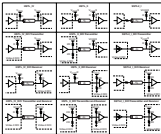


Figure 3-10: I/O Usage Examples